

T-1 3/4 (5mm) BI-COLOR RIGHT ANGLE LED **INDICATOR**

Part Number: WP59CB/GYW

Green Yellow

Features

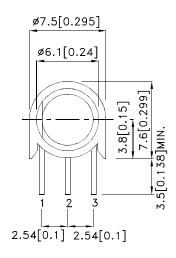
- Pre-trimmed leads for pc board mounting.
- 3 leads with one common lead.
- Black case enhances contrast ratio.
- Wide viewing angle.
- High reliability life measured in years.
- Housing UL rating: 94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

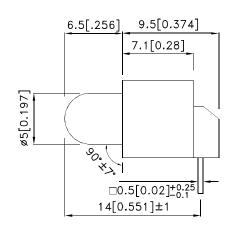
Description

The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

The Yellow source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Yellow Light Emitting Diode.

Package Dimensions





- 1 ANODE GREEN
- 2 COMMON CATHODE
- 3 ANODE YELLOW

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- 3. Lead spacing is measured where the leads emerge from the package.
 4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

SPEC NO: DSAF2080 APPROVED: WYNEC

REV NO: V.4B CHECKED: Allen Liu

DATE: MAR/28/2013 DRAWN: Q.M.Chen

PAGE: 1 OF 6 ERP: 1102001754

Selection Guide

| Part No. | Dice | Lens Type | lv (mcd) [2] @ 20mA | | Viewing Angle [1] |
|------------|--------------------|-----------------|------------------------|------|----------------------|
| | | | Min. | Тур. | 201/2 |
| WP59CB/GYW | Green (GaP) | White Diffused | 50 | 100 | 60° |
| | Yellow (GaAsP/GaP) | Willie Dillused | 20 | 40 | |

Notes:

- 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Luminous intensity/ luminous Flux: +/-15%.
- 3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

| Symbol | Parameter | Device | Тур. | Max. | Units | Test Conditions |
|--------|--------------------------|-----------------|------------|------------|-------|---------------------|
| λpeak | Peak Wavelength | Green Yellow | 565 590 | | nm | Ir=20mA |
| λD [1] | Dominant Wavelength | Green Yellow | 568 588 | | nm | IF=20mA |
| Δλ1/2 | Spectral Line Half-width | Green Yellow | 30 35 | | nm | IF=20mA |
| С | Capacitance | Green Yellow | 15 20 | | pF | VF=0V;f=1MHz |
| VF [2] | Forward Voltage | Green Yellow | 2.2 2.1 | 2.5 2.5 | V | IF=20mA |
| lR | Reverse Current | Green Yellow | | 10 10 | uA | V _R = 5V |

Notes:

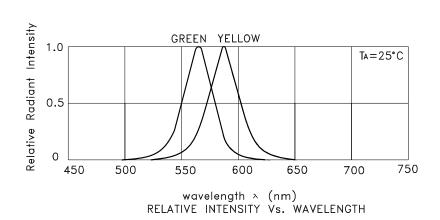
- 1.Wavelength: +/-1nm.
- Forward Voltage: +/-0.1V.
 Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

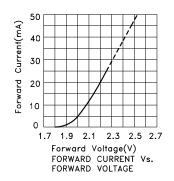
| Parameter | Green | Yellow | Units | | |
|---------------------------------|---------------------|--------|-------|--|--|
| Power dissipation | 62.5 | 75 | mW | | |
| DC Forward Current | 25 | 30 | mA | | |
| Peak Forward Current [1] | 140 | 140 | mA | | |
| Reverse Voltage | Ę | V | | | |
| Operating / Storage Temperature | -40°C To +85°C | | | | |
| Lead Solder Temperature [2] | 260°C For 3 Seconds | | | | |
| Lead Solder Temperature [3] | 260°C For 5 Seconds | | | | |

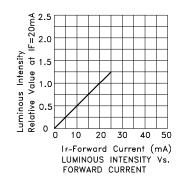
- 1. 1/10 Duty Cycle, 0.1ms Pulse Width.
- 2. 2mm below package base.3. 5mm below package base.

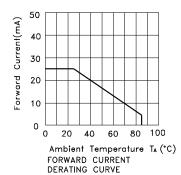
DATE: MAR/28/2013 SPEC NO: DSAF2080 **REV NO: V.4B** PAGE: 2 OF 6 APPROVED: WYNEC **CHECKED: Allen Liu** ERP: 1102001754 DRAWN: Q.M.Chen

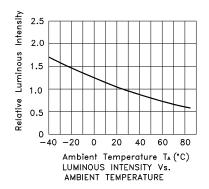


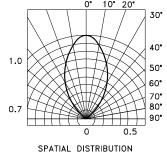
WP59CB/GYW Green







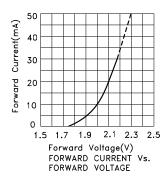


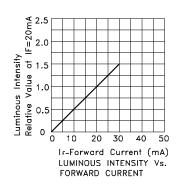


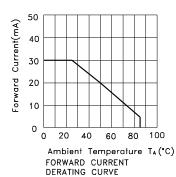
 SPEC NO: DSAF2080
 REV NO: V.4B
 DATE: MAR/28/2013
 PAGE: 3 OF 6

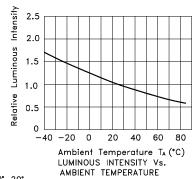
 APPROVED: WYNEC
 CHECKED: Allen Liu
 DRAWN: Q.M.Chen
 ERP: 1102001754

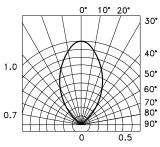
Yellow





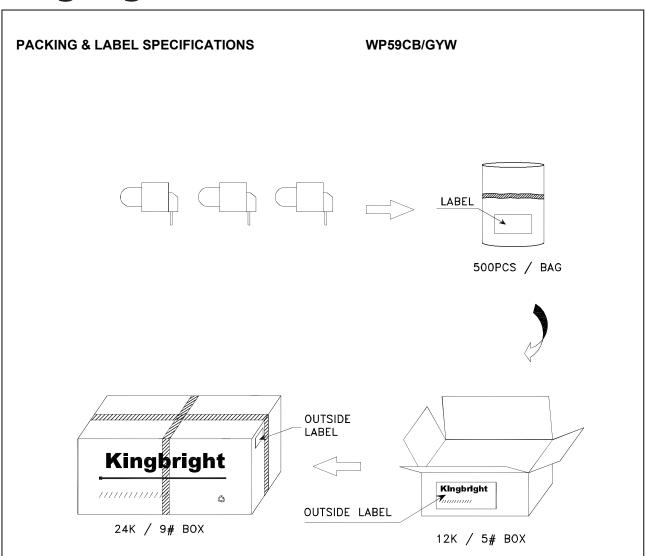


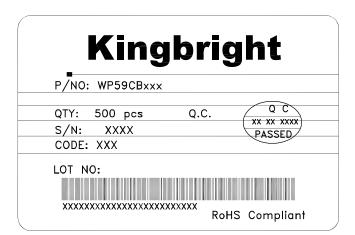




SPATIAL DISTRIBUTION

SPEC NO: DSAF2080 REV NO: V.4B DATE: MAR/28/2013 PAGE: 4 OF 6
APPROVED: WYNEC CHECKED: Allen Liu DRAWN: Q.M.Chen ERP: 1102001754

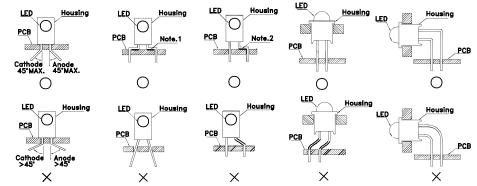




SPEC NO: DSAF2080 APPROVED: WYNEC REV NO: V.4B CHECKED: Allen Liu DATE: MAR/28/2013 DRAWN: Q.M.Chen PAGE: 5 OF 6 ERP: 1102001754

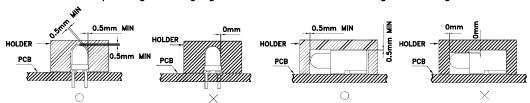
PRECAUTIONS

 The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead—forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

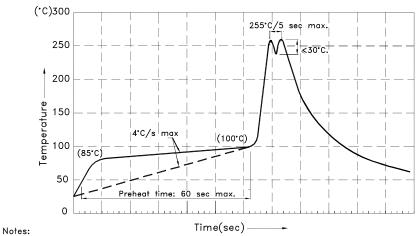


"() " Correct mounting method "imes" Incorrect mounting method

2. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



- 3. The tip of the soldering iron should never touch the lens epoxy.
- 4. Through—hole LEDs are incompatible with reflow soldering.
- 5. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.
- 6. Recommended Wave Soldering Profiles:



- 1.Recommend pre—heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
- 2.Peak wave soldering temperature between 245°C \sim 255°C for 3 sec (5 sec max).
- 3.Do not apply stress to the epoxy resin while the temperature is above 85°C.
- 4.Fixtures should not incur stress on the component when mounting and during soldering process.
- 5.SAC 305 solder alloy is recommended.
- 6.No more than one wave soldering pass.

All design applications should refer to Kingbright application notes available at http://www.KingbrightUSA.com/ApplicationNotes

SPEC NO: DSAF2080 REV NO: V.4B DATE: MAR/28/2013 PAGE: 6 OF 6

APPROVED: WYNEC CHECKED: Allen Liu DRAWN: Q.M.Chen ERP: 1102001754